



Marianna Perdiki

Synthesis And Characterization Of Copper Oxide Nanowires

CuO Nanowires as Semiconductors



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Marianna Perdiki

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Abstract

Copper oxide nanowires are source of a great interest in the scientific community due to numerous properties and the wide range of possible applications of this nanoscale material. In this project, CuO nanowire growth was achieved using an atmospheric pressure chemical vapor deposition (APCVD) reactor via dry oxidation at various temperatures and gas flow rates. CuO nanowire synthesis was studied on a variety of different substrates, such as 50 nm Cu/p⁺Si, 100 nm Cu/p⁺Si, thin copper foil (0.12 mm thickness) and thick copper foil (1mm thickness). The growth of nanowires was successful, when the substrate was a thin copper foil. In particular, CuO nanowires were fabricated at temperatures between 400 °C and 700 °C. The growth lasted one hour using oxygen flow rate of 100 standard cubic centimeters per minute (sccm). In our experiments, copper oxide nanowires formed at 600 °C with ramp rate = 30 °C/min. They have 2.5 - 9.0 μm length and diameters smaller than 200 nm. Afterwards, transport of nanowires on p⁺Si(001) was studied using an ultrasonicator. The copper oxidized layers were ultrasonicated with isopropanol at various times in order to have only nanowires without pieces of oxide layer on silicon substrate. The best results of transfer were found when the ultrasonication lasted twenty seconds. In this case, 1.82 ml of solution with nanowires was dropped on the surface of silicon, which was successfully covered with copper oxide nanowires. The photoluminescence (PL) spectrum at 300 K consisted of a broad peak centered at 419 nm. Moreover, time correlated single photon counting (TCSPC) PL measurements were taken at room temperature (RT) for 400 nm emission wavelength over a time span of 50 ns. These measurements show that the PL decay can be well described by a linear combination of three exponentials suggesting a complex energy level scheme structure for the CuO NWs.

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